



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-05-08
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS3150U	HNZI*Z70P81R	A	ZA41	2018-05-08
Amount	UoM	Unit type	ST ECOPACK Grade	
107	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.50X2.16X3.68	1	J bend	
Comment	Package: SMB CLIP (SOD 6 NEW)			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015			
Query			Response
1 - Product(s) meets EU RoHS requirement without any exemptions			FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)			FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)			TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions			FALSE
Exemption Id.	Description		
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)		

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.02	Die	168
Lead	2.33	Soft solder	21766

QueryList :Customer	
Query	Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				
Query				Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				FALSE
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				FALSE
Hasardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
O	O	O	O	O

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HNZJ*Z70P81R									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	1.597	mg	supplier	die	Silicon (Si)	7440-21-3		1.547	mg	968691	14458				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.010	mg	6262	93				
				supplier	metallization	Gold (Au)	7440-57-5		0.007	mg	4384	65				
				supplier	passivation	Nickel (Ni)	7440-02-0		0.007	mg	4383	65				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	626	9				
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	1252	19				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.009	mg	5636	84				
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	626	9				
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1252	19				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.011	mg	6888	103				
				Leadframe & Clip	Copper and its alloy	44.314	mg	Supplier	Alloy	Copper (Cu)	7440-50-8		44.293	mg	999526	413953
								Supplier	Alloy	Zinc (Zn)	7440-66-6		0.002	mg	46	20
								Supplier	Alloy	Iron (Fe)	7439-89-6		0.004	mg	90	37
Supplier	Alloy	Iron Phosphide(FeP)	26508-33-8						0.015	mg	338	140				
Soft solder	Other organic material	2.518	mg	Supplier	soft solder	Silver (Ag)	7440-22-4		0.063	mg	25020	589				
				Supplier	soft solder	Tin (Sn)	7440-31-5		0.126	mg	50040	1178				
				JIG R	soft solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.329	mg	924940	21766				
Encapsulation	Other organic material	57.553	mg	Supplier	Molding Compound	silica fused	7631-86-9		42.587	mg	739961	398009				
				Supplier	Molding Compound	silica quartz	14808-60-7		11.510	mg	199990	107570				
				Supplier	Molding Compound	phenolic resin	9003-35-4		2.879	mg	50023	26907				
				Supplier	Molding Compound	carbon black	1333-86-4		0.577	mg	10026	5393				
Finishing	Other inorganic material	1.018	mg	Supplier	connection coating	Tin (Sn)	7440-31-5		1.018	mg	1000000	9514				